

QUALITEK[®] 775 WATER SOLUBLE ROSIN FLUX

CORPORATE HEADQUARTERS USA: 315 Fairbank St. Addison, IL • 630-628-8083 • FAX 630-628-6543
EUROPE UK: Unit 9 Apex Ct. Bassendale Rd. Bromborough, Wirral CH62 3RE • 44 151 334 0888 • FAX 44 151 346 1408
ASIA-PACIFIC HEADQUARTERS SINGAPORE: 6 Tuas South St. 5 Singapore 637790 • 65 6795 7757 • FAX 65 6795 7767
PHILIPPINES: Phase 1 Qualitek Ave. Mariveles, Bataan Philippines C-2106 • 6347 935 4163 • FAX 63475613717
CHINA: 3B/F, YiPa Print Bldg. 351 # JiHua Rd., Buji Shenzhen, China 518112 • 86 755 28522814 • FAX 86 755 28522787

Description

Qualitek® 775 is a rosin-based Water Soluble flux designed for high-speed wave soldering applications, circuit board assembly and through-hole applications. Post soldering residue does not require immediate cleaning or rinsing since the residue is not corrosive, like most organic fluxes. 775 residues are effectively removed using standard water cleaning systems without the use of detergent or neutralizer.

Main Features

- ❑ Excellent wettability and hole fill
- ❑ Minimal bridging
- ❑ Immediate cleaning not required
- ❑ Compatible with Lead-Free & Leaded Solder Systems

Technical Data

Flux Classification	Specification	Test Method
Color and Appearance	ORM1	IPC-J-STD-004B
Copper Mirror	Amber Liquid	
Corrosion Test (Cleaned)	Partial removal of copper film	IPC-TM-650 2.3.32
SIR (Cleaned)	Pass	IPC-TM-650 2.6.15
Specific Gravity (g/cm³) @ 25°C	5.99 x 10 ¹⁰ ohms	IPC-TM-650 2.6.3.3
pH Value	0.873 ± 0.006	
Solids (Wt. %)	2.90 – 3.50	
% Halides	4.5 ± 0.5	
	1.9	

(this portion intentionally left blank)

Applications

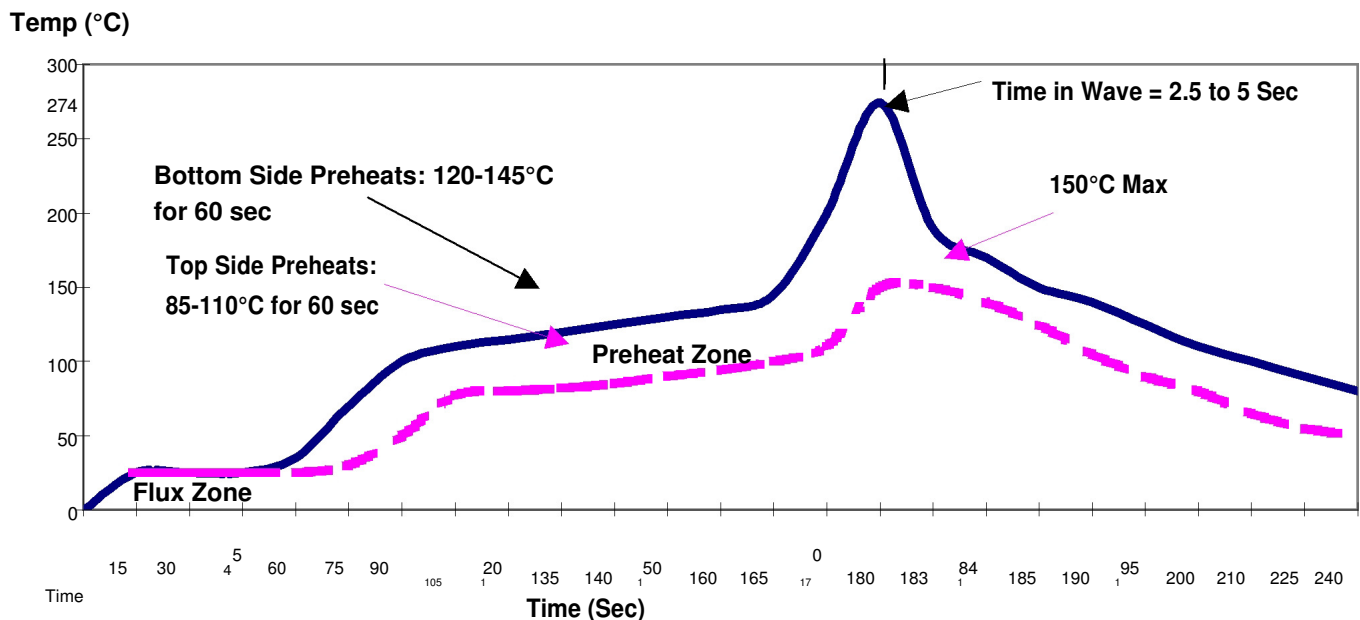
Flux Application

For mass wave soldering of OSP and plated circuit boards, spray, foam or wave fluxing can be utilized to apply this flux. Flux deposition density and uniformity are critical to successful use of low solids water soluble flux. If foam fluxing, the foam fluxer should be supplied with compressed air, which is free of oil and water. The flux tank should be full at all times. The surface of the flux should be 1-½ inches above the top of the flux aerator, or flux stone. Pressure should then be adjusted to produce the optimum foam height with a fine uniform foam head. After fluxing, an air knife should be used to remove excessive flux from the assembly.

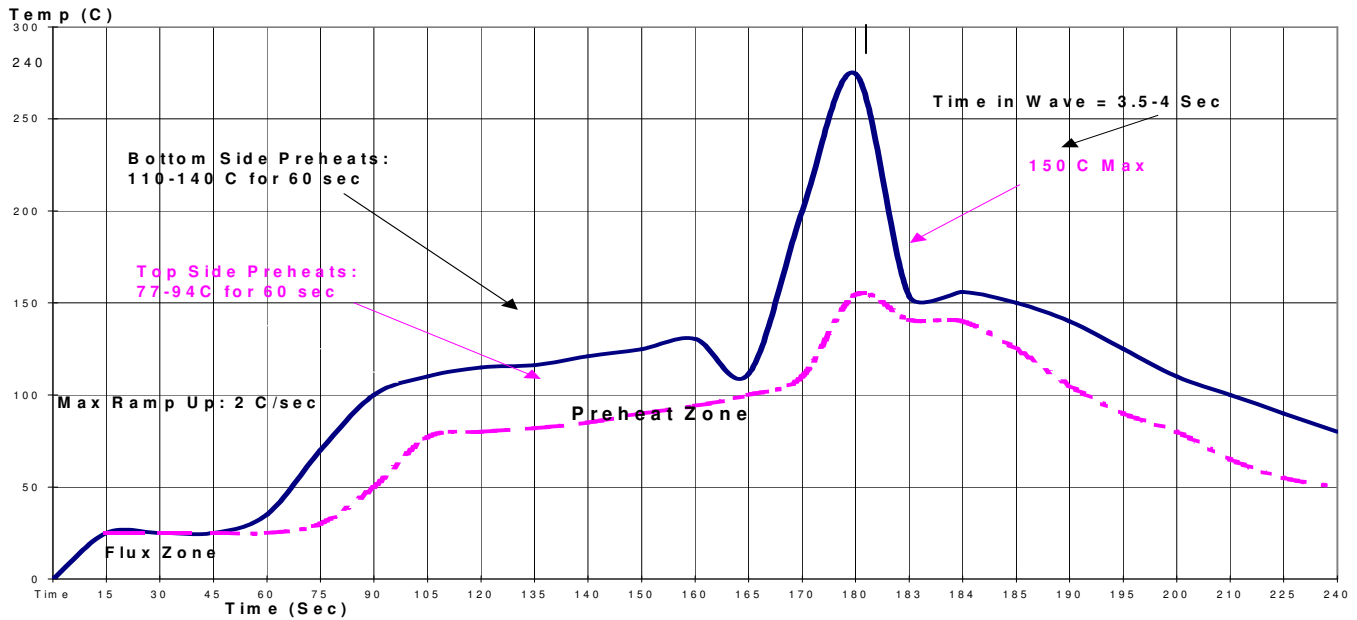
Uniformity of the spray flux coating can be visually checked by running a tempered glass plate (usually supplied by machine manufacturer) through the spray and preheat sections, and inspected before going across the wave.

OPERATING PARAMETERS		TYPICAL LEVEL
Amount of flux		Foam, Wave: 1000-2000 µg/in ² solids Spray: 750-1500 µg/in ² solids
Foam Fluxing Parameters		
	Foam Stone Pore Size	20-50 µm
	Flux Level Above Stone	1-1 ½ inches (25-40mm)
	Chimney Opening	3/8-1/2 inch (10-13 mm)
	Air Pressure	1-2 psi
Top Side Preheat Temperature		190-230 °F (85-110 °C)
Bottom Side Preheat Temperature		65 °F (35 °C) higher than topside
Conveyor Speed		4-6 feet/minute(1.2-1.8 meters/minute)
Contact Time in the Solder (including Chip & Lambda)		2.5-4.5 seconds
Solder Pot Temperature		
	Sn96.5/Ag3.5	500-530 °F (260-276 °C)
	Sn95/Ag5	536-565 °F (280-296 °C)
	Sn99.3/Cu0.7	510-530 °F (265-276 °C)
	SnAgCu	520-530 °F (271-276 °C)
	Sn95/Sb5	536-565 °F (280-296 °C)

TYPICAL Lead Free Wave Solder Profile (SNAGCU)



TYPICAL Leaded Wave Solder Profile (Sn63/Pb37)



Process Control

Control of flux during use is necessary to assure a consistent amount of flux is applied to assemblies. Monitoring and controlling specific gravity is recommended for maintaining the proper flux concentration. Density (specific gravity) can be performed using a hydrometer. Control of the flux can be achieved with 700T thinner to maintain fluxing activity.

Over time debris and contaminants may accumulate in the flux reservoir. Therefore, periodically replacing the flux and cleaning the reservoir is recommended for consistent performance and minimizing debris build-up.

#775 Flux	
Specific Gravity	Thinner Required Fl oz/ga
0.872	0
0.875	6
0.879	12
0.882	17
0.885	22
0.889	26

Flux Residues and Cleaning

As with all water-soluble fluxes, post-soldering cleaning is required. Residues can be easily removed with both hot and cold water, thus; no neutralizer is needed. De-ionized water should be used in the final rinse for cleanliness results beyond MIL-28809A. Spray pressures should be maintained at 20-30 psi and conveyor speed of 3-6 ft. /min.

Storage & Shelf Life

775 Liquid Flux should be stored in a 65-80°F environment away from direct heat and flame. Shelf life is 2 years from date of manufacture.

Packaging

775 Water Soluble Liquid Flux is available in

- 1 Gallon/1 Liter containers
- 5 Gallon/5 Liter containers
- 55 Gallon/20 Liter containers

Disposal

775 contains hazardous ingredients, therefore, the flux should be disposed of in accordance with federal, state and local authority requirements.

Qualitek® is a brand of Qualitek International, Inc.